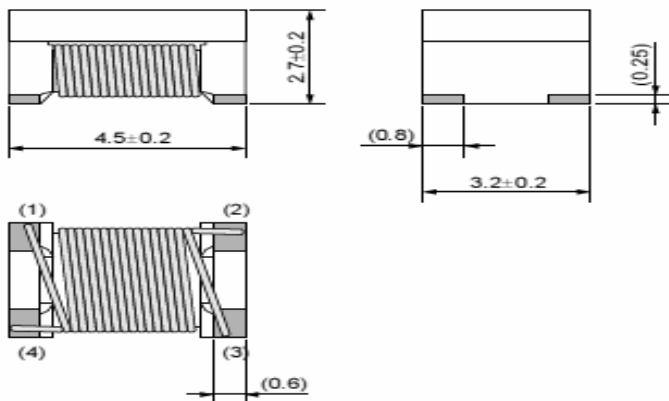


## PACKING DIMENSIONS (mm)



SMW4532	Dimensions
A	$4.5 \pm 0.2$
B	$3.2 \pm 0.2$
C	$2.7 \pm 0.2$
D	$0.25 \pm 0.1$
E	0.8Typ.
F	0.6Typ.

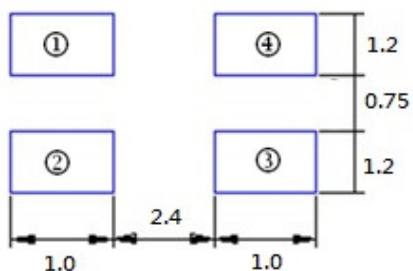
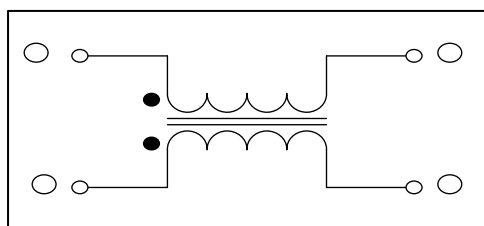
## ELECTRICAL CHARACTERISTICS

P/N	Z( $\Omega$ )		L( $\mu$ H)	DCR ( $\Omega$ )	Idc(mA)	Rated Voltage	Insulation Resistance
	Common Mode		Common Mode				
	Impedance		Inductance	[ Max ]	[ Max ]	Vdc	IR
	at 10MHz		at 100KHz			(V)Typical	(M $\Omega$ )Min.
SMW4532S201XTT	min.	10000	(+50%/-30%)	4.50	100	50	10
	typ.	15000	200				

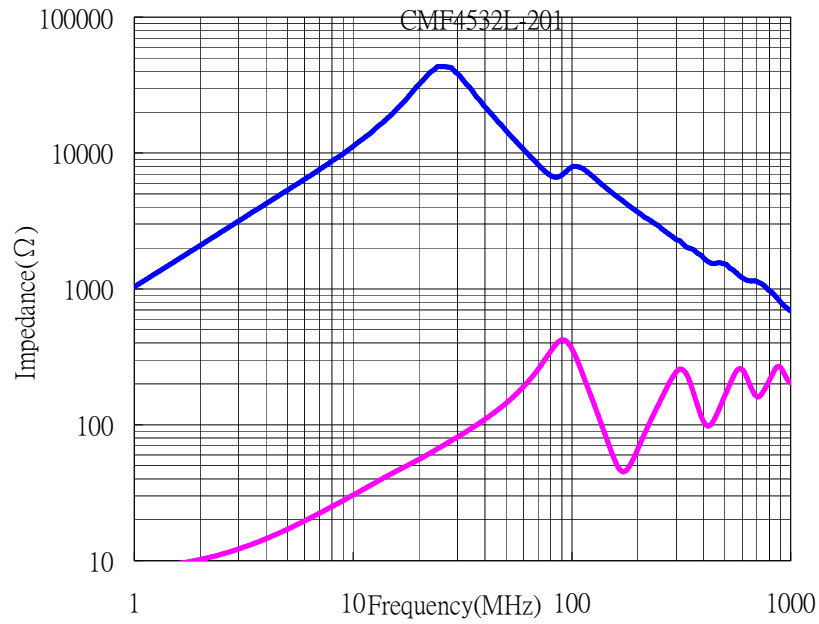
Operating temperature : -25 to +85°C

Storage temp. and humidity : -40 to +85°C ,70%RH max

## Equivalent Circuit & Recommended Footprint



## PERFORMANCE CURVES

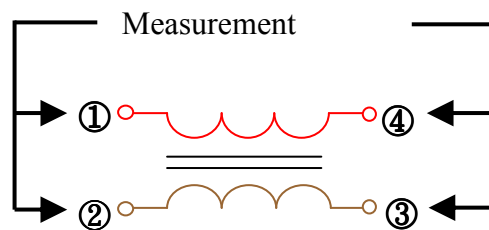


**Test Equipment**

**Impedance / Inductance**

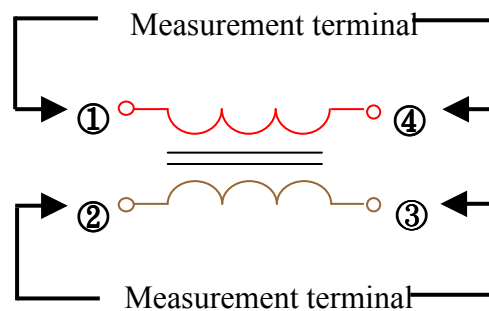
**Measured by using Agilent 4291A RF Impedance Analyzer.**

**Measured by using Microtest 6377 LCR METER.**



**DC Resistance**

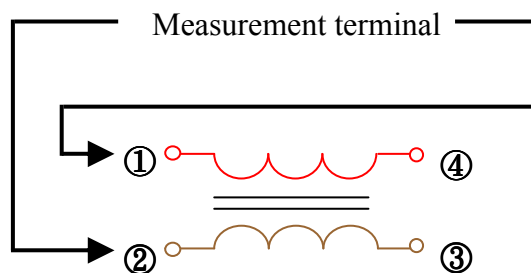
**Measured by using Chroma 16502 mill ohm meter.**

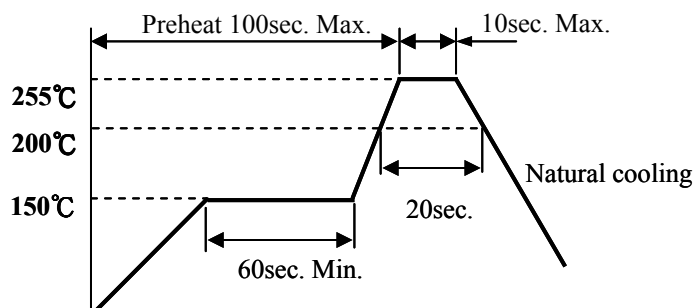


**Insulation Resistance**

**Measured by using Chroma 19073**

**Measurement voltage : 50v ,Measurement time : 60 sec.**

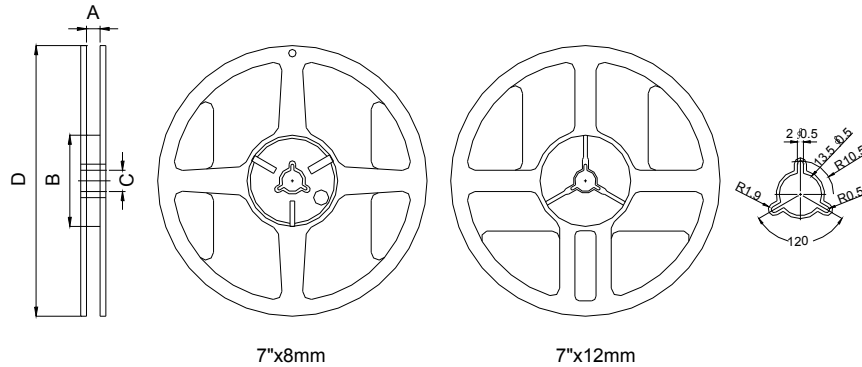


**RECOMMENDED SOLDERING TEMP. GRAPH**

**MECHANICAL RELIABILITY**

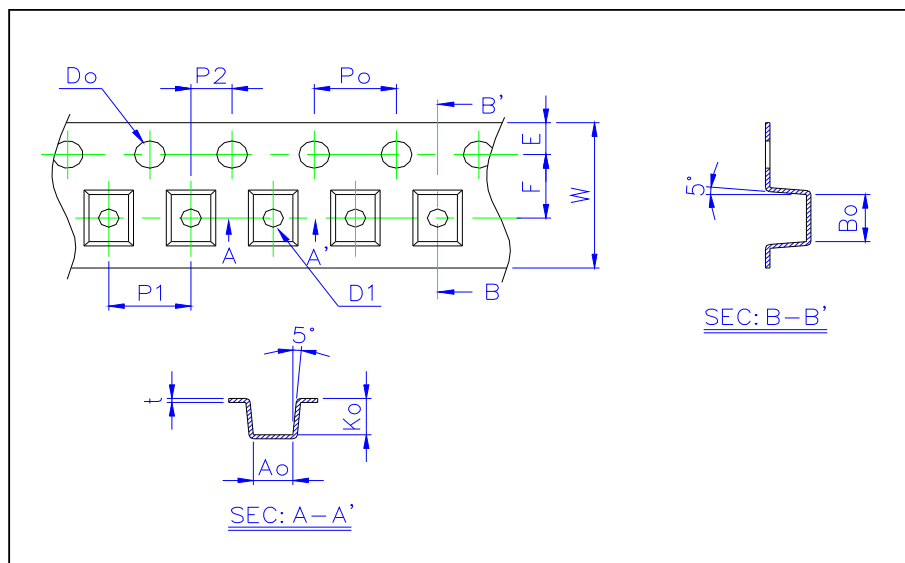
TEST	Specification & Requirement	Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%	Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 245 ±5°C for 4 ±1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within ±15% of initial value	Preheating: 150°C 60secs Solder temperature: 260±5°C Flux: rosin Dip time: 10±0.5 secs

**ENDURANCE RELIABILITY**

TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within ± 15% Without mechanical damage	-65°C, (30 mins) -> room temp. (2 mins) -> 125°C, (30 mins) -> room temp. (2 mins) 50 cycles
Humidity Resistance	Impedance change within ± 15% Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. -40 ±2 °C for total 168 +5/-0 hours
High Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. 125 ±2 °C for total 168 +5/-0 hours

**Reel Dimension & Tape Dimension**


Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2



Size	Ao(mm)	Bo(mm)	Ko(mm)	W(mm)	E(mm)	F(mm)	Po(mm)	P1(mm)	Do(mm)
1210	1.15±0.10	1.40±0.10	0.93±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
1608	1.65±0.10	1.00±0.10	1.18±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
2012	2.35±0.10	1.50±0.10	1.45±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
3216	3.50±0.10	1.88±0.10	2.10±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
4532	3.45±0.10	4.90±0.10	3.05±0.10	12.00±0.20	1.75±0.10	5.50±0.05	4.0±0.05	8.0±0.10	1.5+0.1,-0

**Packaging Quantity(Unit : PCS)**

Chip Size	1210	1608	2012	3216	4532
8mm/ Reel	3000	2000	2000	2000	500